# Specification of Thermoelectric Module TETC3-125-125-125-09CH4.7

## **Description**

The TETC3-125-125-09 is a multistage module designed for greater temperature differential cooling, good for cooling and heating up to 100 °C applications. It is a 125-125-125 couples module in size of 40mm ×40mm (top/bottom). If higher operation or processing temperature is required, please specify, we can design and manufacture according to your special requirements.

#### **Features**

- High Temperature Differential
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

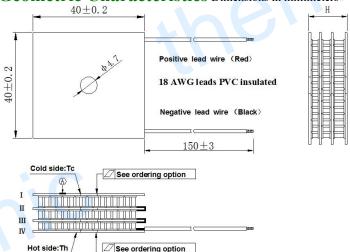
## **Application**

- Infrared (IR) Sensors
- CCD Sensor
- Gas Analyzers
- Calibration Equipment
- CPU cooler and scientific instrument
- Photonic and medical systems
- Guidance Systems

## **Performance Specification Sheet**

Th (°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>	
DT <sub>max</sub> (°C)	104	117	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U <sub>max</sub> (Voltage)	14.3	15.5	Voltage applied to the module at DT <sub>max</sub>	
I <sub>max</sub> (Amps)	8.7	8.7	DC current through the modules at DT <sub>max</sub>	
Q <sub>Cmax</sub> (Watts)	34.5	37	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (Ohms)	1.40	1.49	The module resistance is tested under AC	
Tolerance	10%		For thermal and electricity parameters	

## Geometric Characteristics Dimensions in millimeters



# **Ordering Option**

Suffix	Thickness	Flatness/	Lead wire length(mm)	
	(mm)	Parallelism (mm)	Standard/Optional length	
TF	0: 10.3± 0.4	0: 0.1/0.1	150±3/Specify	
TF	1: 10.3± 0.2	1: 0.05/0.05	150±3/Specify	
Eg. TF11: Thickness10.3±0.2 (mm) and Flatness/ Parallelism 0.05/0.05 (mm)				

## **Manufacturing Options**

#### A. Solder: B. Sealant:

1. T100: BiSn (Tmelt=138°C) 1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217°C) 2. SS: Silicone sealant

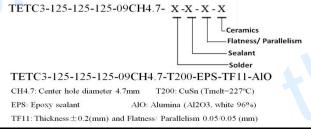
3. T240: SbSn (Tmelt =  $240^{\circ}$ C) 3. EPS: Epoxy sealant

#### C. Ceramics: D. Ceramics Surface Options:

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%) 1. Blank ceramics (not metalized)

2. Aluminum Nitride (AlN) 2. Metalized

## Naming for the Module

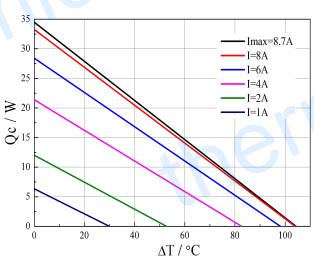


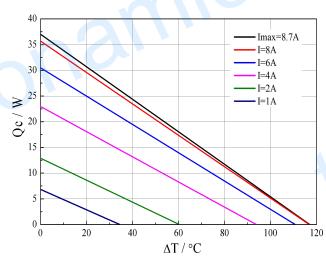
# **Specification of Thermoelectric Module**

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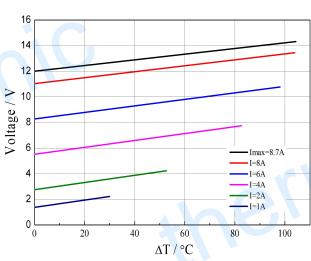
## Performance Curves at Th=27 °C

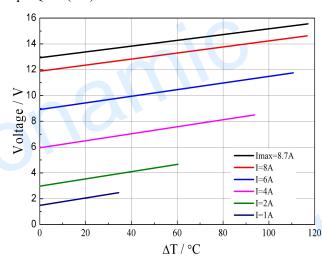
## Performance Curves at Th=50 °C



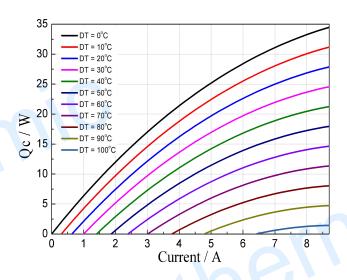


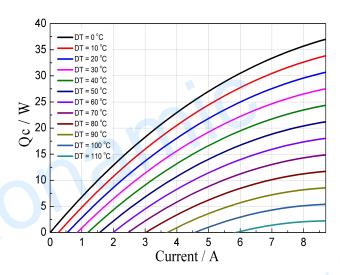
Standard Performance Graph Qc= f(DT)





Standard Performance Graph V= f(DT)



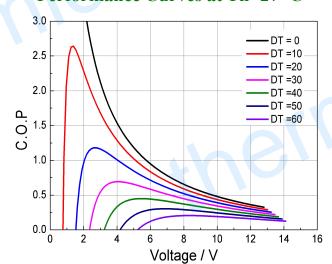


Standard Performance Graph Qc= f(I)

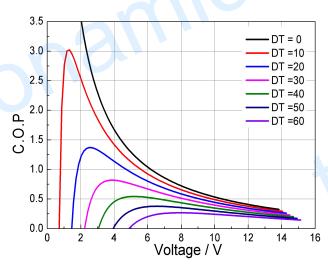
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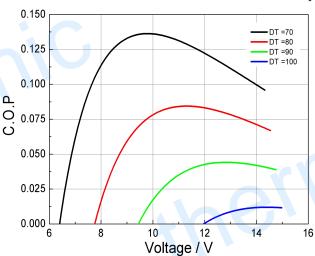
## Performance Curves at Th=27 °C

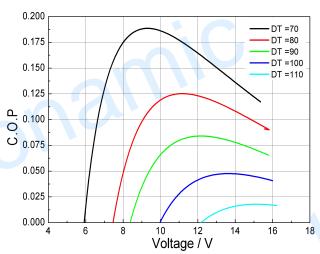


#### Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 60 °C





Standard Performance Graph COP = f(V) of DT ranged from 70 to 100/110 °C

**Remark:** The coefficient of performance (COP) is the cooling power Qc/Input power ( $V \times I$ ).

## **Operation Cautions**

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Storage module below 100 °C
- Operation below I<sub>max</sub> or V<sub>max</sub>
- Work under DC

Note: All specifications subject to change without notice.